

SOD-323 Plastic-Encapsulate Diodes

BAS16J High-speed switching diodes

Features

- High switching speed: $t_{rr} \leq 4 \text{ ns}$
- Low leakage current
- Repetitive peak reverse voltage: $V_{RRM} \leq 100 \text{ V}$
- Low capacitance
- Reverse voltage: $V_R \leq 100 \text{ V}$
- Small SMD plastic packages

Applications

- High-speed switching
- General-purpose switching

Description

High-speed switching diodes, encapsulated in small Surface-Mounted Device (SMD) plastic packages.

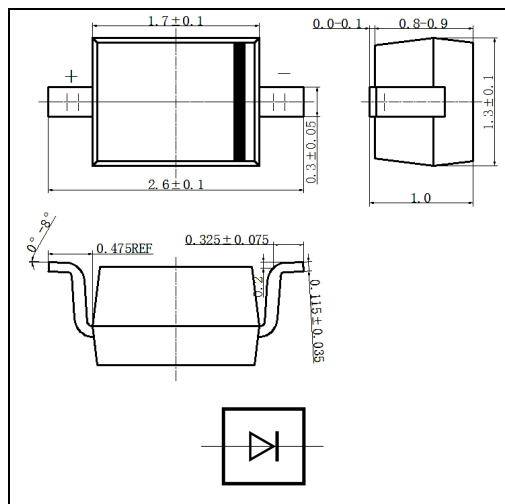
Maximum Ratings ($T_a=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak repetitive reverse voltage	100	V	
V_R	Reverse voltage	100	V	
I_F	Forward current ¹⁾	250	mA	
I_{FRM}	Repetitive peak forward current @ $t_p \leq 0.5 \text{ ms}$; $\delta \leq 0.25$	500	mA	
I_{FSM}	Non-repetitive peak forward current square wave; $T_{j(\text{init})} = 25^\circ\text{C}$	$t_p = 1 \mu\text{s}$	4	A
		$t_p = 1 \text{ ms}$	1	A
		$t_p = 1 \text{ s}$	0.5	A
P_{tot}	Total power dissipation $T_{amb} \leq 25^\circ\text{C}$ ²⁾	550	mW	
T_j	Junction temperature	150	$^\circ\text{C}$	
T_{amb}	Ambient temperature	-65 ~ +150	$^\circ\text{C}$	
T_{stg}	Storage temperature	-65 ~ +150	$^\circ\text{C}$	
$R_{\theta JA}$	Thermal resistance from junction to ambient ²⁾	230	K/W	
$R_{\theta JS}$	Thermal resistance from junction to solder point ³⁾	55	K/W	

1. Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

2. Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

3. Soldering point of cathode tab.

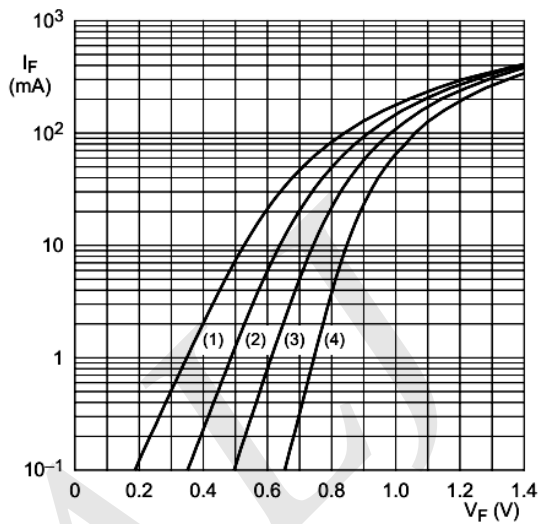


Electrical Characteristics ($T_a=25^{\circ}\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_F	Forward voltage ¹⁾	$I_F = 1\text{mA}$			715	mV
		$I_F = 10\text{mA}$			855	mV
		$I_F = 50\text{mA}$			1	V
		$I_F = 150\text{mA}$			1.25	V
I_R	Reverse current	$V_R = 25\text{V}$			30	nA
		$V_R = 80\text{V}$			0.5	μA
		$V_R = 25\text{V}; T_j = 150^{\circ}\text{C}$			30	μA
		$V_R = 80\text{V}; T_j = 150^{\circ}\text{C}$			50	μA
C_d	Diode capacitance	$f = 1\text{MHz}; V_R = 0\text{V}$			1.5	pF
t_{rr}	Reverse recovery time	$I_F = 10\text{mA}; I_R = 10\text{mA};$ $R_L = 100\Omega;$ $I_{R(\text{meas})} = 1\text{mA}$			4	ns
V_{FR}	Forward recovery voltage	$I_F = 10\text{mA}; t_r = 20\text{ns}$			1.75	V

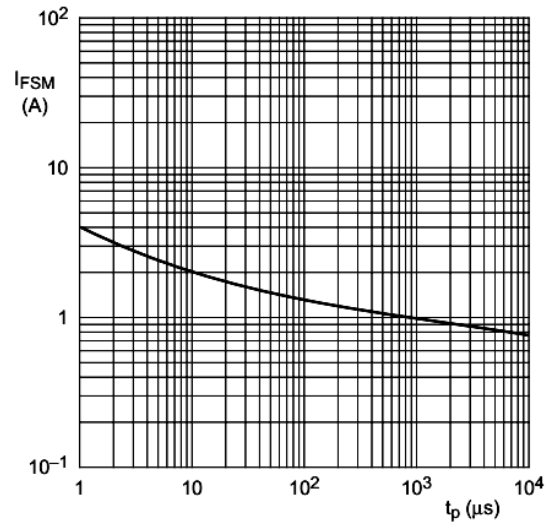
1. Pulse test: $t_p \leq 300\mu\text{s}; \delta \leq 0.02.$

Typical Characteristics



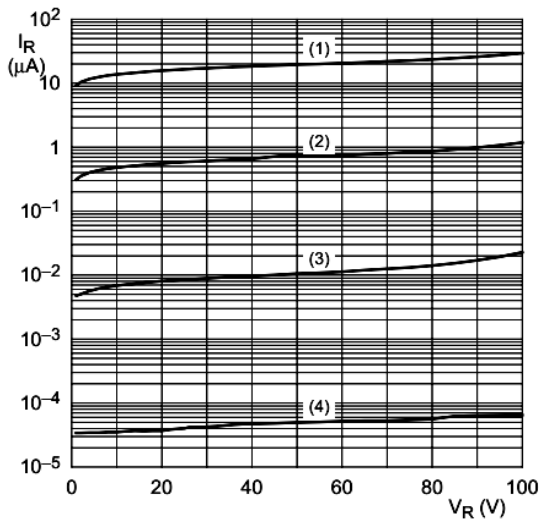
- (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (4) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 1. Forward current as a function of forward voltage; typical values



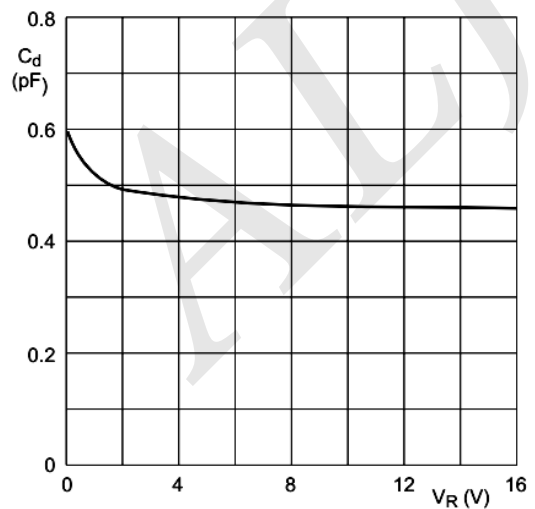
Based on square wave currents.
 $T_{j(init)} = 25\text{ }^{\circ}\text{C}$

Fig 2. Non-repetitive peak forward current as a function of pulse duration; maximum values



- (1) $T_{amb} = 150\text{ }^{\circ}\text{C}$
- (2) $T_{amb} = 85\text{ }^{\circ}\text{C}$
- (3) $T_{amb} = 25\text{ }^{\circ}\text{C}$
- (4) $T_{amb} = -40\text{ }^{\circ}\text{C}$

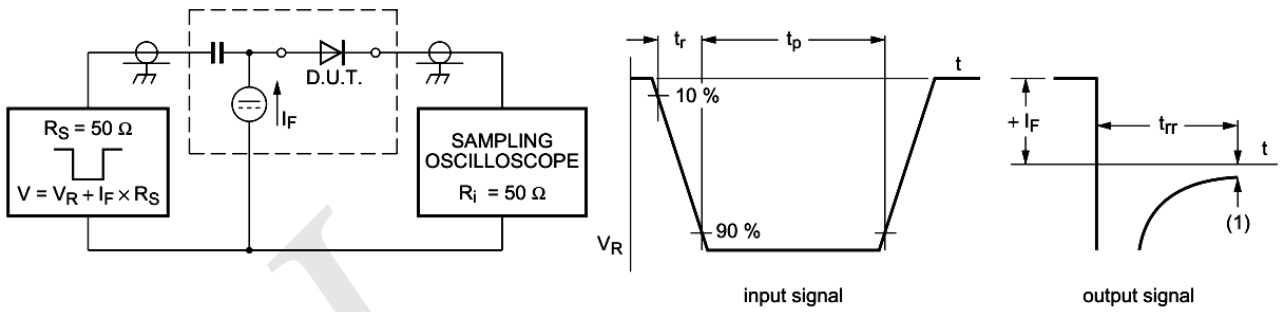
Fig 3. Reverse current as a function of reverse voltage; typical values



$f = 1\text{ MHz}; T_{amb} = 25\text{ }^{\circ}\text{C}$

Fig 4. Diode capacitance as a function of reverse voltage; typical values

Test information

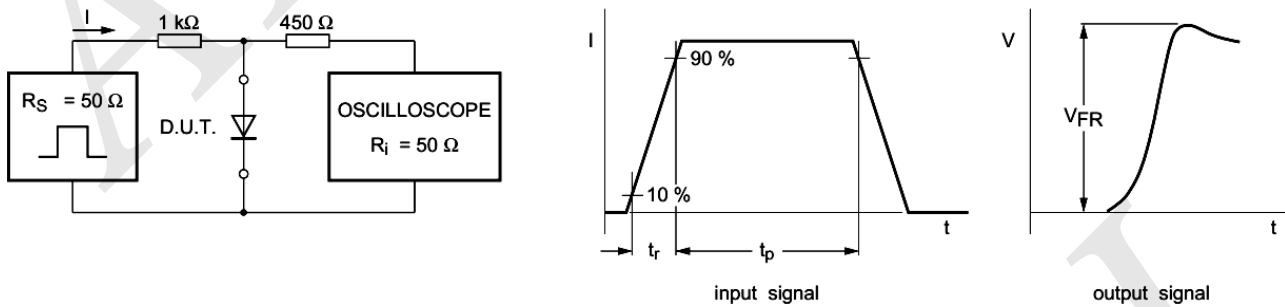


(1) $I_R = 1 \text{ mA}$

Input signal: reverse pulse rise time $t_r = 0.6 \text{ ns}$; reverse voltage pulse duration $t_p = 100 \text{ ns}$; duty cycle $\delta = 0.05$

Oscilloscope: rise time $t_r = 0.35 \text{ ns}$

Fig 5. Reverse recovery time test circuit and waveforms



Input signal: forward pulse rise time $t_r = 20 \text{ ns}$; forward current pulse duration $t_p \geq 100 \text{ ns}$; duty cycle ≤ 0.005

Fig 6. Forward recovery voltage test circuit and waveforms